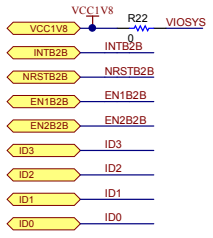


HSI2C_SYS

Multiphase config	J1	J2	J3	J01	J02	J23	Assembly Variant
0 (4)	B	B	B	Y	Y	Y	001
1 (3-1)	B	B	A	Y	Y	N	002
2 (2-2)	B	A	B	Y	N	Y	003
3 (2-1-1)	B	A	A	Y	N	N	004
4 (1-1-1-1)	A	A	A	N	N	N	005
5 - 9 (4)	B	B	B	Y	Y	Y	001

J0 should be assembled in all configurations



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 Project Title: Small Solution Power for Server Card

1 2 3 4 5 6

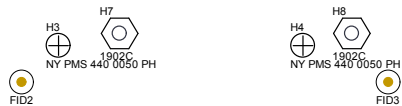
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A

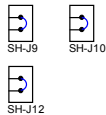


PCB Number: TIDA-00596
PCB Rev: 001

PCB
LOGO
Texas Instruments



LBL1
DNP
Size: 1.25" x 0.25"



ZZ1
Assembly Note
Place Female Shunts at J4 (both positions) and J5.

D

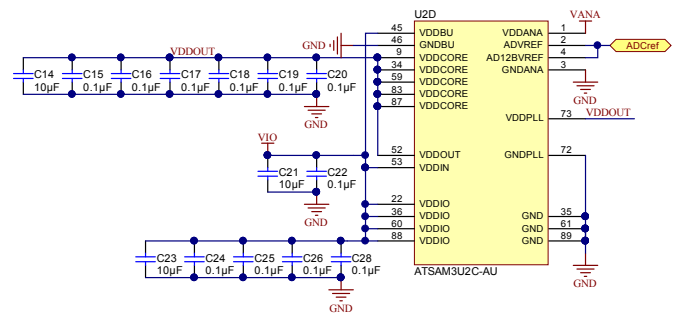
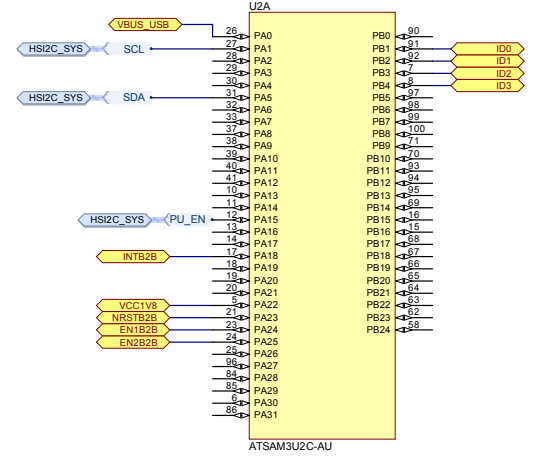
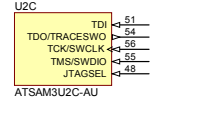
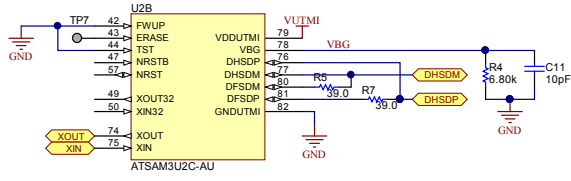
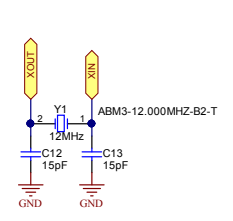
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Designed for Public Release		Mod. Date: 4/8/2014	
Project Title: Small Solution Power for Server Card			
Number: TIDA-00596	Rev: E1	Sheet Title: Mechanics	
Assembly Variant: 004	Sheet: 2 of 3	File: TIDA-00596_Sheet2_SchDoc	
Drawn By: Not shown in title block		Engineer: Jarmo Laurila	Contact: http://www.ti.com/support

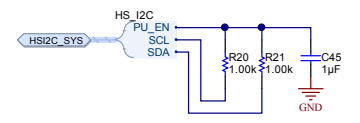
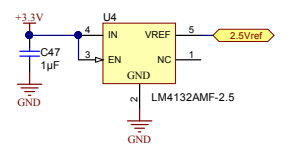
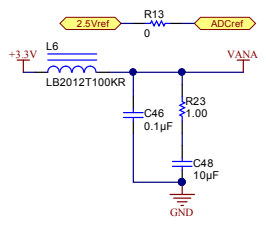
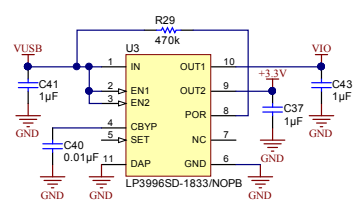
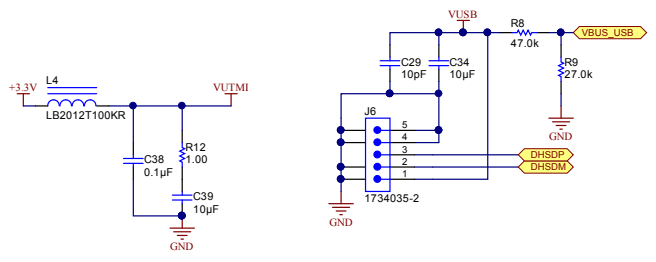
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1 2 3 4 5 6



LDO1: 1.8 V (150 mA), VDDIO for SAMSU
LDO2: 3.3 V (300 mA), 3.3V generic supply



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